

In the Specification:

Page 1, after the title, insert the following heading and paragraphs:

**--RELATED APPLICATIONS**

This is a U.S. national stage of application No. PCT/DE03/003189, filed on 24 September 2003.

This patent application claims the priority of German patent application no. 10245945.2 filed 30 September 2002, the disclosure content of which is hereby incorporated by reference.--

Page 1, before line 5, insert the following heading:

**--FIELD OF THE INVENTION--**

Page 1, before line 9, insert the following heading, and amend the paragraph beginning at lines 9, 12 and 16 as follows:

**--BACKGROUND OF THE INVENTION--**

A light source module of this type is described e.g. in the published US patent application ~~DE 100 51 159 A1~~ No. 2003/01788627.

~~This patent application claims the priority of German patent application 102 45 945.2, the disclose content of which is hereby incorporated by reference.~~

~~The German application bearing the application number 102 29 067 which has not yet been published,~~ Published US Patent Application No. 2004/0089898 discloses e.g. arranging an LED in a frame and potting the region between frame and LED with potting composition. In order to

obtain a reflector, preferably reflective potting composition is first filled into the region between frame and LED and subsequently complete potting is effected using clear potting composition.

Page 2, before line 7, insert the following heading, and amend the paragraphs beginning at lines 8, 11, 16 as follows:

**-- SUMMARY OF THE INVENTION--**

~~Therefore, the invention is based on the~~ One object of ~~demonstrating the invention is to provide a~~ light source module which withstands even greatly varying temperature conditions.

~~This object is achieved according to~~ and other objects are attained in accordance with one aspect of the invention by virtue of the fact that the LEDs are surrounded by a frame, a potting composition is arranged between the frame and the LEDs, and the frame has expansion joints.

By introducing the expansion joints into the frame, it is possible to use the technology disclosed in the ~~[[patent application 102 29 067 - published after the priority date -]]~~ above-mentioned published US patent application no. 2004/0089898, namely the technology of placing a frame onto the LEDs and potting the interspace with potting composition.

Page 2, amend the paragraphs beginning at lines 28 and 32 as follows:

~~In accordance with a preferred embodiment, the~~ The frame ~~[[is ]]~~ can be segmented into a plurality of frame parts by expansion joints.

In this case, a frame part ~~preferably has~~ can have a maximum of four cutouts in which LEDs can be arranged. In the case where the frame is produced from plastic and the metal carrier is

produced from aluminum, this number of cutouts per frame part guarantees a high reliability and functionality even in the event of high temperature fluctuations.

Page 3, amend the paragraph beginning at line 1 as follows:

The LEDs ~~are~~ can be arranged in the light source module ~~preferably~~ in a grid, e.g. in a grid of 4.5 mm in eight columns and four rows, and may be used for realizing an LED light source for an HUD system (HUD = Head-up Display) in a motor vehicle.

Page 3, delete the paragraph beginning at line 13 in its entirety.

Page 3, line 17, replace the heading with the following new heading:

**--BRIEF DESCRIPTION OF THE DRAWINGS--**

Page 4, before line 4, insert the following heading::

**-- DETAILED DESCRIPTION OF THE DRAWINGS --**

Page 4, amend the paragraph beginning at line 12 as follows:

The carrier substrate 2 is ~~generally~~ composed of a material exhibiting good thermal conductivity and ~~is in each case arranged by means of~~ it includes an interposed insulating layer 3 and also a carrier layer 5 on a metal carrier 4, which serves not only as a carrier but also as a heat sink. The metal carrier 4 is preferably composed of aluminum or copper in order to obtain a high dissipation of heat.

Page 4, amend the paragraph beginning at line 33 as follows:

Since silicon layers can be applied in extremely thin fashion and have a good thermal conductivity, these layers 6 and 7 are ideal for the electrical insulation of and the dissipation of heat from the optoelectronic components 1 via the carrier substrates 2 to the metal carrier 4.

Page 6, amend the paragraph beginning at line 17 as follows:

The expansion joints 13, as illustrated in Figure 1, may likewise also be formed as a complete separation of the frame 10 at this location. In the case of the complete separation of the frame 10, a separating cut ~~[[14]]~~ 13a is generally provided in the expansion joint 13, thereby producing separate frame parts 10a and 10b.

Page 7, amend the paragraph beginning at line 24 as follows:

At the locations of the expansion joints 13, the frame has a trapezoidal cutout on both sides, ~~which cutout may either be chosen such that the thin web already takes up the deformation or, as illustrated~~ results in forming a thin portion ("web") of the frame. This thin portion can be easily bent or deformed and can, thereby, compensate for deformations. As in Figure 1, the remaining web is severed by means of a separating cut ~~[[14]]~~ 13a at this location using a sawing device.

Page 8, amend the paragraph beginning at line 1 as follows:

Figures 4A and 4B show the frames described in Figures 2 and 3, and Figures 5A and 5B show the metal carrier 4 with ~~applied insulating and carrier layer and also~~ a flexible printed circuit board 18 arranged thereon with a flexible conductor connection 19~~[[, the]]~~. The carrier

substrates 2 and also the optoelectronic components 1 ~~being~~ are applied on the flexible printed circuit board 18.

Page 8, amend the paragraph beginning at line 15 as follows:

The severing of the expansion joints 13 by means of the sawing device may ~~already~~ be effected just after this method step or else not until after the potting of the cutouts 14.

Page 8, between lines 18 and 20, insert the following new paragraph:

--The circuit board 18 differs from circuit board 8 of Figure 1 in that circuit board 18 is a flexible circuit board. Furthermore, in the embodiment shown in Figure 5A carrier substrate 2 and components 1 are arranged on the flexible circuit board 18 whereas in Figure 1 carrier substrate 2 is directly applied on metal carrier 4.--